

Electronic Patent Application Fee Transmittal

Application Number:	10553647			
Filing Date:	14-Oct-2005			
Title of Invention:	RESIN COMPOSITION FOR MOLD USED IN FORMING MICROPATTERN, AND METHOD FOR FABRICATING ORGANIC MOLD THEREFROM			
First Named Inventor/Applicant Name:	Tae Wan Kim			
Filer:	Eugene Lieberstein/Audrey de Souza			
Attorney Docket Number:	DE1657			
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U.S. National Stage under 35 USC 371 Filing Fees				
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Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	2501	1	755	755
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Total in USD (\$)				1055